101795-H14 General Specifications

Mechanical

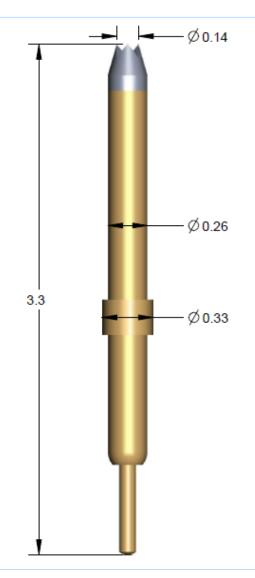
- Typical Application: BGA
- Minimum Device Pitch: 0.4 mm
- Work Force: 21 gf @ 0.38 mm Recommended travel
- Operating Temperature Range: -55°C to 120°C
- Device Side Contact: 4-point Crown Tip
- PCB Side Contact: Conical Radius Tip

Electrical

- Bandwidth @ -1 dB: up to 20 GHz
- Contact Resistance: < 50 mΩ average
- Current Carrying Capability: 3.0 A
 - Measured in free air

Plating

- Device Side Plunger: Homogenous alloy
- PCB Side Plunger: Gold plated
- Barrel: Gold plated
- Spring: Gold plated



Mouser Electronics

Authorized Distributor

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Smiths Interconnect: 101795-H14